

T-1 3/4 (5mm) Infrared Emitting Diode

Features

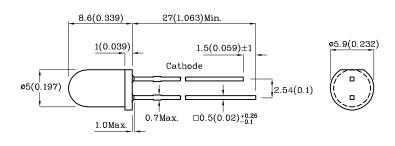
- Radial / Through hole package
- \bullet Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant

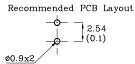
Dec 07,2020





Package Schematics





Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	THI (GaAlAs)	Unit			
Reverse Voltage	V_{R}	5	V		
Forward Current	I_{F}	50	mA		
Forward Current (Peak) 1/100 Duty Cycle 10us Pulse Width	iFS	1200	mA		
Power Dissipation	P_{D}	85	mW		
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C		
Storage Temperature	Tstg	-40 ~ +85			
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

A Relative $\overline{\text{Humidity between 40\%}}$ and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

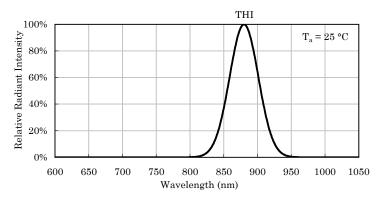
Operating Characteristics (T _A =25°C)		THI (GaAlAs)	Unit V V	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	1.3		
Forward Voltage (Max.) (I _F =20mA)	V_{F}	1.6		
Reverse Current (Max.) (V _R =5V)	$I_{ m R}$	10	μA	
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λΡ	880*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$\triangle \lambda$	50	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	90	pF	

Part Number	Emitting Material	Lens-color	Radiant Intensity CIE127-2007* (Po=mW/sr) @20mA		Radiant Intensity CIE127-2007* (Po=mW/sr) @50mA		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
			min.	typ.	min.	typ.		
XTHI12W	GaAlAs	Water Clear	6*	14*	12*	24*	880*	20°

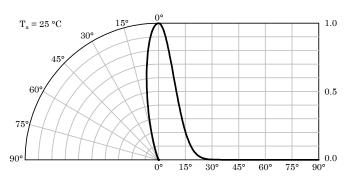
^{*}Radiant intensity value and wavelength are in accordance with CIE127-2007 standards.





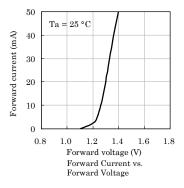


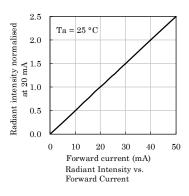
Relative Intensity Vs. CIE Wavelength

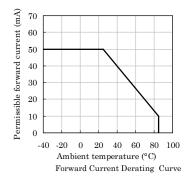


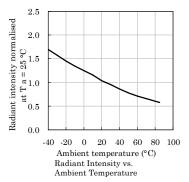
Spatial Distribution

♦ THI

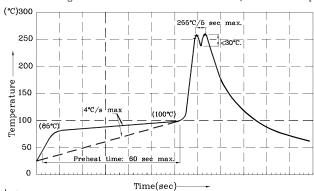








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes: 1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C 2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec

(5 sec max).

 $3.\mathrm{Do}$ not apply stress to the epoxy resin while the temperature is above $85^{\circ}\mathrm{C}$. $4.\mathrm{Fixtures}$ should not incur stress on the component when mounting and

during soldering process. 5.SAC 305 solder alloy is recommended.

6. No more than one wave soldering pass

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux),

the typical accuracy of the sorting process is as follows:

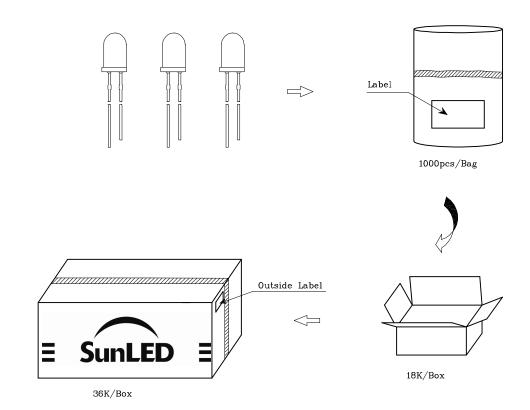
- 1. Radiant Intensity / Luminous Flux: +/-15%
- 2. Forward Voltage: +/-0.1V

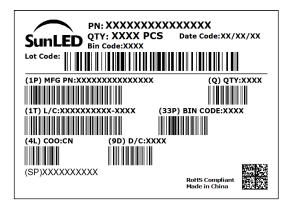
Note: Accuracy may depend on the sorting parameters.





PACKING & LABEL SPECIFICATIONS





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